

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE 200 PIN DDR MINI DIMM, 0.60 mm LEAD CENTERS	ISSUE A	DATE DEC 2004	MO-258	SHEET 2 OF 5
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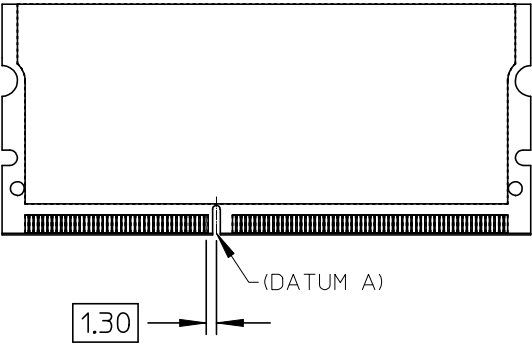
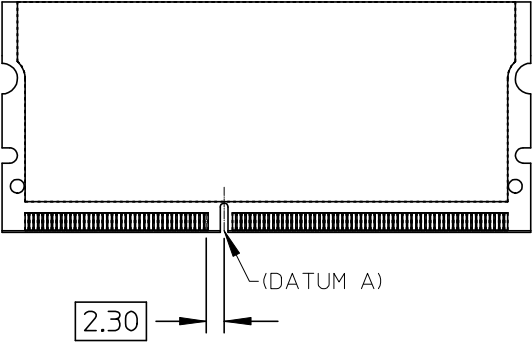
COMMON DIMENSION TABLE

SYMBOL	MIN	NOM	MAX	NOTES
A1	6.00 BSC			
A2	4.00	--	--	5,8
A3	20.00 BSC			
A4	10.00 BSC			
D	68.65	68.80	68.95	
D1	24.60 BSC			
D2	64.80 BSC			
E	--	--	3.80	5
e1	23.40 BSC			
e2	35.40 BSC			
N	200			
ISSUE	--			
REF	14-			
NOTES	1,2,3			

SDRAM VARIATIONS

	AA			AB			
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	NOTES
A	29.85	30.00	30.15	29.85	30.00	30.15	
D3	1.30 BSC			2.30 BSC			4
D4	1.30 BSC			2.30 BSC			
D5	6.50 BSC			5.50 BSC			
ISSUE	A			A			
REF	14-069			14-069			
NOTES	1,2,3			1,2,3			

MECHANICAL KEYING
(FRONT VIEWS)

POWER SUPPLY 9	4
1.8 V	
x.x V	

NOTES :

1. DIMENSIONS AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
2. TOLERANCES ON ALL DIMENSIONS ± 0.15 UNLESS OTHERWISE SPECIFIED.
3. ALL DIMENSIONS ARE mm.

△₄ APPLICATION NOTE :
VARYING THE POSITION OF THE NOTCH IDENTIFIES THE OPERATIONAL
VOLTAGE : 1.8 VOLT (xA). x.x VOLT (xB).

△₅ DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED
ON BOTH SIDES.

△₆ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES
PLATING AND/OR METALIZATION.

△₇ APPLICATION NOTE :
RECOMMENDED PLATING FOR CONTACT PADS ARE ;
1) PREFERABLE PLATING : ELECTROLYTIC GOLD PLATING 0.76 MICROMETERS
MINIMUM OVER ELECTROLYTIC NI 2.00 MICROMETERS MINIMUM.
2) ALTERNATIVE PLATING : GOLD PLATING 0.05-0.75 MICROMETERS OVER
NI 2.00 MICROMETERS MINIMUM MUST USE AN ELECTRONIC CONTACT GRADE
CORROSIVE BARRIER LUBRICANT.

△₈ BORDER OF COMPONENT AREA.

△₉ THE JC-42.5 COMMITTEE CONTROLS THE INFORMATION IN THIS COLUMN.
IT IS SHOWN HERE FOR REFERENCE ONLY, AND IS SUBJECTED TO CHANGE.

△₁₀ APPLICATION NOTE :
EDGE OF CONTACT PADS SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

△₁₁ THE ADDITION OF THIS BEVEL IS A FABRICATION OPTION AND IS NOT REQUIRED.
THE BEVEL AIDS THE INSERTION OF THE MODULE INTO THE CONNECTOR.
THE BEVEL IS NOT TO HIT THE PLATED CONTACTS.

△₁₂ PATENT CLAIM :
IT HAS BEEN STATED THAT U.S. PATENT NO. 5,227,664 (HELD BY HIATCHI)
MAY BE RELATED TO CERTAIN IMPLEMENTATIONS OF THIS PACKAGE OUTLINE

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